

# FJT44 **NPN Epitaxial Silicon Transistor**

· High Voltage Transistor



September 2006

## Absolute Maximum Ratings\* T<sub>x</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	500	V
V <sub>CEO</sub>	Collector-Emitter Voltage	400	V
V <sub>EBO</sub> Emitter-Base Voltage           I <sub>C</sub> Collector Current		6	V
		300	mA
P <sub>C</sub>	Collector Dissipation $(Ta = 25 \ ^{o}C)$	2	W
TJ	Junction Temperature	150	°C
T <sub>STG</sub>	Storage Temperature Range	- 55 ~ +150	°C

\* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150°C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## Thermal Characteristics\* T<sub>a</sub>=25°C unless otherwise noted

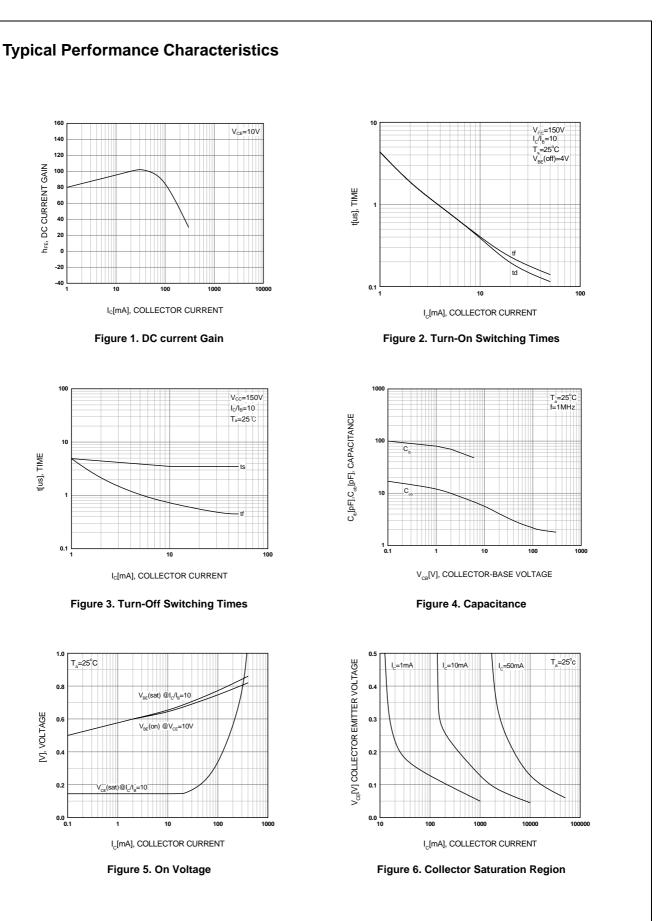
Symbol	Parameter	Value	Units
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	62.5	°C/W

Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm. mounting pad for the collector lead min. 6 cm <sup>2</sup>

# Electrical Characteristics\* T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>CBO</sub>	Collector-Base Breakdown Voltage	I <sub>C</sub> = 100uA, I <sub>E</sub> = 0	500			V
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 1mA, I <sub>B</sub> = 0	400			V
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage	$I_{E} = 100 \mu A, \ I_{C} = 0$	6			V
I <sub>CBO</sub>	Collector-Base Cutoff Current	$V_{CB} = 400 V I_{E} = 0$			100	nA
I <sub>CES</sub>	Collector-Emitter Cutoff Current	$V_{CE} = 400V, V_{BE} = 0$			500	nA
I <sub>EBO</sub>	Emitter-Base Cutoff Current	$V_{CE} = 4V, I_{C} = 0$			100	nA
h <sub>FE</sub>	DC Current Gain		40 50 45 40		200	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$\begin{split} I_{C} &= 1 m A, \ I_{B} = 0.1 m A \\ I_{C} &= 10 m A, \ I_{B} = 1 m A \\ I_{C} &= 50 m A, \ I_{B} = 5 m A \end{split}$			0.4 0.5 0.75	V V V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1mA			0.75	V
C <sub>obo</sub>	Output Capacitance	V <sub>CB</sub> = 20V, I <sub>E</sub> = 0, f = 1MHz			7	pF

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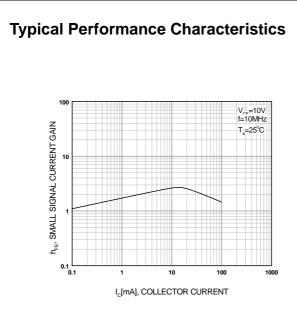
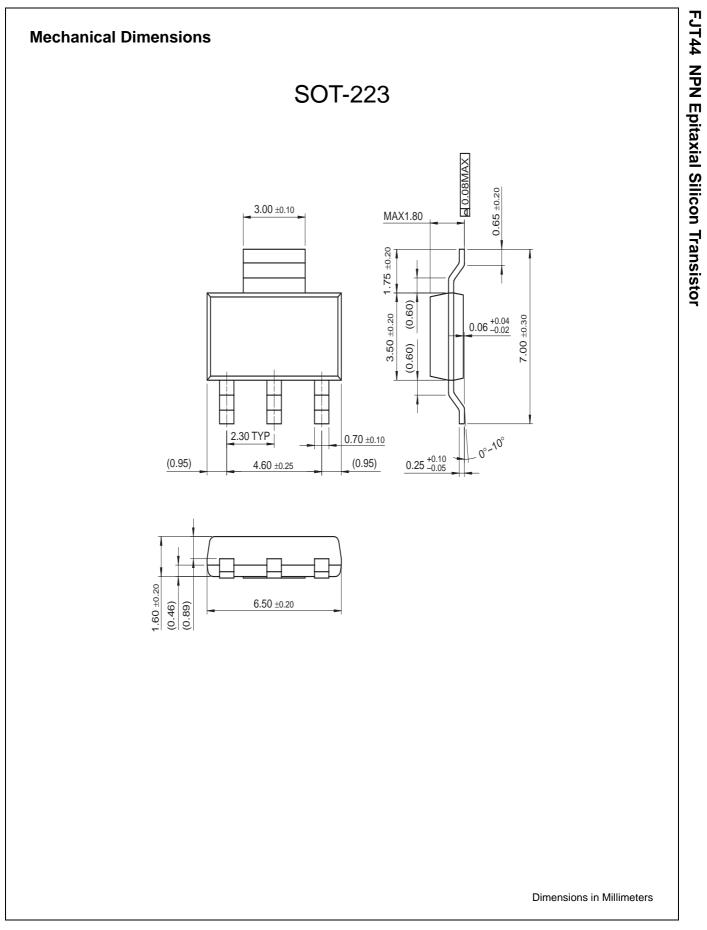


Figure 1. High Frequency Current Gain



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